

**POLISHING PAD AND METHOD OF FABRICATING SEMICONDUCTOR
DEVICE USING THE SAME**

CROSS-REFERENCE TO RELATED APPLICATION(S)

5 **[0001]** This application claims priority to Korean Patent Application No. 10-2020-0126784, filed on September 29, 2020 and No. 10-2020-0128580, filed on October 06, 2020, the disclosure of which is incorporated herein by reference in its entirety.

Technical Field

10 **[0002]** The present disclosure relates to a pad which is applied to a polishing process, and to a technique for applying this pad to a method for fabricating a semiconductor device.

Description of the Related Art

15 **[0003]** A chemical mechanical planarization (CMP) or chemical mechanical polishing (CMP) process may be performed for various purposes in various technical fields. The CMP process is performed on a predetermined polishing target surface of a polishing target, and may be performed for the purposes of planarization of the polishing target surface, removal of aggregated materials, reduction of crystal lattice damage, and removal of scratches and contamination sources.

20 **[0004]** CMP process technologies for semiconductor fabrication processes may be classified according to the quality of a polishing target layer or the surface shape after polishing. For example, they may be classified into a CMP process for single silicon and a CMP process for polysilicon according to the quality of a polishing target layer, and may also be classified into CMP processes for various oxide layers, which are distinguished by the types of impurities, or CMP processes for metal layers such as tungsten (W), copper (Cu), aluminum (Al), ruthenium (Ru) and tantalum (Ta) layers. In addition, according to

25

the surface shape after polishing, they may be classified into a process of reducing the roughness of the substrate surface, a process of planarizing a stepped portion caused by multilayer circuit wiring, and a device isolation process for selectively forming circuit wiring after polishing.

5 **[0005]** A plurality of CMP processes may be applied in a process for fabricating a semiconductor device. A semiconductor device includes a plurality of layers, and each layer includes a complex and fine circuit pattern. In addition, in recent semiconductor devices, the size of an individual chip has been reduced, and the pattern of each layer has become more complex and finer. Accordingly, the CMP process in the process of
10 fabricating a semiconductor device has been expanded not only for the purpose of planarizing circuit wiring, but also for isolation between circuit wirings and the improvement of the wiring surface, and as a result, more sophisticated and reliable CMP performance has been required.

15 **[0006]** A polishing pad which is used in this CMP process is a component for processing a polishing target surface to a required level through friction, and may be considered one of elements which are most important in the thickness uniformity of a polishing target after polishing, and the flatness and quality of the polishing target surface.

SUMMARY

20 **[0007]** One embodiment of the present disclosure provides a polishing pad, the polishing surface state of which may be maintained at the same level as the initial state even with the passage of time during a polishing process, so that the long-term polishing performance thereof does not deteriorate, and which has suitable physical properties such as hardness, tensile strength and elongation, and thus may achieve a desired level of removal rate and a
25 defect prevention effect when applied to a polishing process.

5 [0008] Another embodiment of the present disclosure provides a method for fabricating a semiconductor device, which shows high process efficiency in polishing of a semiconductor substrate, and achieves an effect in that the polishing target surface of the semiconductor substrate shows an appropriate removal rate and the lowest level of defects as final polishing results.

10 [0009] In one embodiment of the present disclosure, there is provided a polishing pad including a polishing layer, wherein the nuclear magnetic resonance (NMR) ^{13}C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak is about 5:1 to about 10:1.

15 [0010] In one embodiment of the present disclosure, there is provided a polishing pad wherein the area ratio of the first peak to the second peak is about 10:1 to about 10:5, and the area ratio of the first peak to the third peak is about 10:5 to about 10:10.

20 [0011] In one embodiment of the present disclosure, there is provided a polishing pad wherein the polishing layer includes a cured product of a preliminary composition containing a urethane-based prepolymer, the nuclear magnetic resonance (NMR) ^{13}C spectrum of the preliminary composition shows a fourth peak and a fifth peak in descending order of peak position (ppm) at 16 ppm to 20 ppm, and the area ratio of the fourth peak to the fifth peak is 1:1 to 10:1.

25 [0012] In one embodiment of the present disclosure, there is provided a polishing pad wherein the preliminary composition contains a reaction product of an isocyanate compound and a polyol compound, the isocyanate compound includes an aromatic

diisocyanate compound, and the polyol compound includes a low-molecular-weight polyol having a weight-average molecular weight (Mw) of about 100 g/mol to less than about 300 g/mol and a high-molecular-weight polyol having a weight-average molecular weight (Mw) of about 300 g/mol to about 1,800 g/mol.

5 **[0013]** In one embodiment of the present disclosure, there is provided a polishing pad wherein the aromatic isocyanate compound includes 2,4-toluene diisocyanate (2,4-TDI), and the preliminary composition contains a urethane-based prepolymer including at least one of a first unit structure derived from 2,4-TDI subjected to urethane reaction at one end, and a second unit structure derived from 2,4-TDI subjected to urethane reaction at both
10 ends.

[0014] In one embodiment of the present disclosure, there is provided a polishing pad wherein the preliminary composition has an isocyanate group content of 5 wt% to 11 wt%.

[0015] In one embodiment of the present disclosure, there is provided a polishing pad wherein the polishing layer has a value of 0.1 to 0.6 as calculated according to Equation 1
15 below:

[0016] [Equation 1]

$$\frac{M_p - M_n}{M_w - M_n}$$

[0017]

[0018] wherein Mw, Mn and Mp are the molecular weights of the processed composition, measured by gel permeation chromatography (GPC),

20 **[0019]** Mw is the weight-average molecular weight of the depolymerized composition,

[0020] Mn is the number-average molecular weight of the depolymerized composition, and

[0021] Mp is the peak molecular weight of the depolymerized composition.

[0022] In one embodiment of the present disclosure, there is provided a polishing pad

wherein the processed composition has a number-average molecular weight (M_n) of 1,800 g/mol to 2,800 g/mol, a weight-average molecular weight (M_w) of 2,000 g/mol to 3,000 g/mol, and a peak molecular weight(M_p) of 2,000 g/mol to 3,000 g/mol.

5 **[0023]** In one embodiment of the present disclosure, there is provided a polishing pad wherein the processed composition has a polydispersity index (PDI, M_w/M_n) of 1 to 1.2.

[0024] In one embodiment of the present disclosure, there is provided a polishing pad wherein the polishing layer has a tensile strength of 18 N/mm² to 22 N/mm² and a hardness (Shore D) of 35 to 55.

10 **[0025]** In another embodiment of the present disclosure, there is provided a method for producing a polishing pad, the method including steps of: i) preparing a preliminary composition containing a reaction product of an isocyanate compound and a polyol compound; ii) preparing a composition for producing a polishing layer containing the preliminary composition, a foaming agent and a curing agent; and iii) producing a polishing layer by curing the composition for producing a polishing layer, wherein the
15 nuclear magnetic resonance (NMR) ¹³C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of
20 the third peak to the second peak is about 5:1 to about 10:1.

[0026] In one embodiment of the present disclosure, there is provided a method for producing a polishing pad, wherein the area ratio of the first peak to the second peak is about 10:1 to about 10:5, and the area ratio of the first peak to the third peak is about 10:5 to about 10:10.

25 **[0027]** In one embodiment of the present disclosure, there is provided a method for

producing a polishing pad, wherein the nuclear magnetic resonance (NMR) ^{13}C spectrum of the preliminary composition shows a fourth peak and a fifth peak in descending order of peak position (ppm) at 16 ppm to 20 ppm, and the area ratio of the fourth peak to the fifth peak is 1:1 to 10:1.

5 **[0028]** In one embodiment of the present disclosure, there is provided a method for producing a polishing pad, wherein the polishing layer has a value of 0.1 to 0.6 as calculated according to Equation 1 below:

[0029] [Equation 1]

$$\frac{\text{Mp}-\text{Mn}}{\text{Mw}-\text{Mn}}$$

[0030]

10 **[0031]** wherein Mw, Mn and Mp are the molecular weights of the processed composition, measured by gel permeation chromatography (GPC)

[0032] Mw is the weight-average molecular weight of the depolymerized composition,

[0033] Mn is the number-average molecular weight of the depolymerized composition, and

15 **[0034]** Mp is the peak molecular weight of the depolymerized composition.

[0035] In one embodiment of the present disclosure, there is provided a method for producing a polishing pad, wherein the prepolymer composition is a urethane-based prepolymer, the urethane-based prepolymer has an isocyanate (NCO) group content of 5 to 11 wt%, and the molar ratio of the NH_2 group of the curing agent to the isocyanate (NCO) group of the urethane-based prepolymer in the composition for producing an polishing layer in step ii) is 0.6 to 0.99.

20

[0036] In another embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, the method including steps of: providing a polishing pad including a polishing layer; and placing the polishing target surface of a polishing

target so as to be in contact with the polishing surface of the polishing layer and then polishing the polishing target while rotating relative to each other, wherein the polishing target includes a semiconductor substrate, the nuclear magnetic resonance (NMR) ¹³C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak is about 5:1 to about 10:1.

[0037] In one embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, wherein the polishing layer has a value of 0.1 to 0.6 as calculated according to Equation 1 below:

[0038] [Equation 1]

$$\frac{M_p - M_n}{M_w - M_n}$$

[0039]

[0040] wherein Mw, Mn and Mp are the molecular weights of the processed composition, measured by gel permeation chromatography (GPC),

[0041] Mw is the weight-average molecular weight of the depolymerized composition,

[0042] Mn is the number-average molecular weight of the depolymerized composition, and

[0043] Mp is the peak molecular weight of the depolymerized composition.

[0044] In one embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, wherein the semiconductor substrate includes a silicon dioxide (SiO₂) layer, the polishing target surface is the surface of the silicon dioxide (SiO₂) layer, the average removal rate of the silicon dioxide layer is 1,500 Å/min to 2,500 Å/min,

and the number of surface defects on the polishing target surface after completion of the polishing is 5 or less.

5 [0045] In one embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, wherein the rotating speed of each of the polishing target and the polishing pad is 10 rpm to 500 rpm.

[0046] In one embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, further including a step of supplying a polishing slurry onto the polishing surface of the polishing layer, wherein the polishing slurry is supplied at a flow rate of 10 ml/min to 1,000 ml/min.

10

BRIEF DESCRIPTION OF THE DRAWINGS

[0047] FIG. 1 schematically illustrates a section of a polishing pad according to an embodiment.

15 [0048] FIG. 2 schematically illustrates a process drawing of a method for fabricating a semiconductor device according to an embodiment.

[0049] FIG. 3 is a schematic diagram illustrating an exemplary preliminary composition, a cured structure, and a processed composition.

DESCRIPTION OF SPECIFIC EMBODIMENTS

20 [0050] The advantages and features of the present disclosure, and the way of attaining them, will become apparent with reference to the embodiments described below. However, the present disclosure is not limited to the embodiments disclosed below and may be embodied in a variety of different forms. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the present disclosure to those skilled in the art. The scope of the present disclosure should be

25

defined only by the appended claims.

[0051] In the drawings, the thicknesses of various layers and regions are exaggerated for clarity. In addition, in the drawings, the thicknesses of some layers and regions are exaggerated for convenience of illustration. Throughout the specification, like reference numerals refer to like components.

[0052] In addition, in the present specification, when a part, such as a layer, film, region, plate, or the like, is referred to as being “on” or “above” another part, it not only refers to a case where the part is directly above the other part, but also a case where a third part exists therebetween. Conversely, when any part is referred to as being “directly above” another part, it refers to a case where a third part does not exist therebetween. In addition, when a part, such as a layer, film, region, plate, or the like, is referred to as being “below” or “under” another part, it not only refers to a case where the part is directly below the other part, but also a case where a third part exists therebetween. Conversely, when any part is referred to as being “directly below” another part, it refers to a case where a third part does not exist therebetween.

[0053] In addition, in the present specification, the area ratio of peaks in the nuclear magnetic resonance (NMR) spectrum is interpreted as falling within the scope of the claims if the number average value determined by calculating the area ratio at least five times in the same manner for the same polishing layer is within the corresponding range. In addition, the area ratio of the peaks may be obtained as integration values of the corresponding peaks in the nuclear magnetic resonance (NMR) spectrum.

[0054] In one embodiment of the present disclosure, there is provided a polishing pad including a polishing layer, wherein the nuclear magnetic resonance (NMR) ^{13}C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a

closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak is about 5:1 to about 10:1.

5 **[0055]** The polishing layer is a cured product composed of compounds having certain chemical structures, and the final polishing performance thereof, such as removal rate and the degree of defects may be determined according to the chemical structure of each of the compounds and the bonding structure and bonding force of each repeating unit constituting the chemical structure. The compounds included in the polishing layer include various
10 types of chemical bonding structures, and when the polishing layer is treated under certain treatment conditions, the bonding may be broken or maintained depending on the bonding strength of each bonding structure. Accordingly, the shape of the nuclear magnetic resonance (NMR) ¹³C spectrum of the processed composition of the polishing layer is changed.

15 **[0056]** Specifically, the polishing layer according to one embodiment may be characterized in that the nuclear magnetic resonance (NMR) ¹³C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a
20 second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak is about 5:1 to about 10:1. That is, the polishing layer is composed of compounds having chemical bonding structures corresponding to the spectral characteristics, and thus the effect of greatly improving the polishing performance of the polishing pad may be obtained. More specifically, the
25 polishing layer has a degree of polymer bonding satisfying the above-described area ratio

of the third peak to the second peak in the nuclear magnetic resonance (NMR) ^{13}C spectrum of the processed composition that satisfies the above-mentioned condition, and exhibits physical properties (such as hardness and elongation) corresponding thereto, and as a result, may realize polishing performance such as a desired level of removal rate (RR).

5 **[0057]** For example, the area ratio of the third peak to the second peak may be about 5:1 to about 10:1, for example, about 5:1 to 8:1. Through the result that the area ratio of the third peak to the second peak satisfies the above range, it can be seen that the polishing layer has chemically bonded repeating units that are partially decomposed under certain conditions and exhibit the above-described peaks, and, at the same time, it can be seen that
10 the polishing layer includes compounds having chemical structures corresponding to the area ratios on the whole. Accordingly, the polishing layer may have appropriate hardness and elongation, and as a result, may achieve a desired removal rate and defect reduction effect.

15 **[0058]** In one embodiment, the processed composition may show an area ratio of the first peak to the second peak of 10:1 to 10:5, and an area ratio of the first peak to the third peak of 10:5 to 10:10.

[0059] For example, the area ratio of the first peak to the second peak may be about 10:1 to about 10:5, for example, about 10:1.00 to about 10:1.60, for example, more than or equal to about 10:1.00, or less than or equal to about 10:1.60.

20 **[0060]** For example, the area ratio of the first peak to the third peak may be from 10:5 to 10:10, for example, more than about 10:5.00, or less than or equal to about 10:10.00, for example, about 10:5.60 to about 10:9.00.

[0061] It can be seen that, when the area ratio of the third peak to the second peak of the processed composition satisfies the above-described range while the area ratio of the first
25 peak to the second peak and the area ratio of the first peak to the third peak satisfy the

above-described ranges, the polishing layer has been cured to an appropriate degree of curing in a curing process during production. Accordingly, the polishing layer may exhibit appropriate hardness and elongation, and as a result, may achieve a desired removal rate and defect reduction effect.

5 **[0062]** In addition, the nuclear magnetic resonance (NMR) ^{13}C spectrum of the processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours showed a higher correlation with the polishing performance of the final polishing pad than that of a processed composition
10 prepared by treatment under other conditions.

[0063] The nuclear magnetic resonance (NMR) ^{13}C spectrum of the processed composition may be determined by comprehensively controlling factors, including the types and contents of raw material monomers, process temperature and pressure conditions, and the types and contents of additives such as a curing agent and a foaming agent, in the
15 process of producing the polishing layer.

[0064] The polishing layer of the polishing pad according to one embodiment of the present disclosure may have a value of 0.1 to 0.6 as calculated according to Equation 1 below:

[0065] [Equation 1]

$$\frac{\text{Mp}-\text{Mn}}{\text{Mw}-\text{Mn}}$$

20 **[0066]**

[0067] wherein Mw, Mn and Mp are molecular weights measured by gel permeation chromatography (GPC) for a depolymerized composition prepared by adding 1 g of the polishing layer to 15 ml of a 0.3 M aqueous solution of KOH and depolymerizing the polishing layer in a closed container at 150°C for 48 hours,

[0068] Mw is the weight-average molecular weight of the depolymerized composition,
[0069] Mn is the number-average molecular weight of the depolymerized composition,
and
[0070] Mp is the peak molecular weight of the depolymerized composition.

5 [0071] Depending on the type and content of a curing agent that may be included in the production of the polishing layer, the equivalents of curing reactive groups such as an amine group (-NH₂) and an alcohol group (-OH) in the curing agent and an isocyanate group (-NCO) in the prepolymer are determined, and the structures of the compounds in the polishing layer are determined.

10 [0072] The final urethane-based cured structure of the polishing pad is determined by these factors. The final urethane-based curing structure may lead to the physical/mechanical properties of the polishing layer, such as hardness, tensile strength, and elongation.

15 [0073] The polishing pad is a process product that may be applied to various polishing processes, and the defect rate and production quality of process products produced using the polishing pad are greatly affected by the physical properties of the polishing pad. For various polishing processes, it is necessary to finely control the surface properties of the polishing layer in order to apply the polishing layer not only to a bulk-level polishing process, but also to micro- and nano-level fine polishing processes, and even if there is no
20 significant difference in absolute value for each physical property, this insignificant difference may lead to a great difference in the polishing properties.

[0074] The polishing layer is a cured product composed of compounds having certain chemical structures, and a difference appears depending on the chemical structures of the compounds and the bonding structure and bonding force of the repeating unit constituting
25 each of the chemical structures.

[0075] The compounds included in the polishing layer include various types of chemical bonding structures, and when the polishing layer is treated under certain treatment conditions, the bonding may be broken or maintained depending on the bonding force of each bonding structure.

5 [0076] Based on this property, the polishing layer of the present disclosure is depolymerized, and the weight-average molecular weight (Mw), number-average molecular weight (Mn) and peak molecular weight (Mp) of the depolymerized composition are measured and substituted into Equation 1 above. When the values are included within the ranges specified in the present disclosure, the compounds constituting the polishing
10 layer exhibit physical properties attributable to their chemical structures.

[0077] The physical/mechanical properties of the polishing layer are closely related to the occurrence of defects on a semiconductor substrate in a polishing process. Although the physical/mechanical properties of the polishing layer may have an effect of increasing the average removal rate and the pad cutting rate, a problem arises in that the occurrence
15 of defects on the semiconductor substrate is relatively increased.

[0078] Specifically, a polishing pad that is used in the CMP process supports the processing pressure applied to a semiconductor substrate and functions to transfer a slurry into the wafer surface. In addition, the polishing pad presses the polishing particles contained in the slurry vertically against the wafer surface and horizontally rolls the
20 particles to ensure smooth polishing.

[0079] The polishing pad having these functions exhibits elastic behavior and viscoelastic behavior, which are behavioral properties of a polymer material, with respect to a given load, and comes into direct contact with the semiconductor substrate during polishing, thus affecting the polishing result.

25 [0080] In particular, the polishing pad of the present disclosure has excellent hardness,

tensile and elongation properties, and thus may reduce the occurrence of defects on the semiconductor substrate.

[0081] Equation 1 means that, when the polishing layer is depolymerized under specific depolymerization conditions, the structures of the compounds constituting the polishing layer are decomposed under the depolymerization conditions, and the physical and/or chemical properties of the polishing layer may be confirmed by measuring values for the decomposed compounds.

[0082] That is, if the value of Equation 1 above, which is a physical and/or chemical index given to the polishing layer by the compounds constituting the polishing layer due to their chemical structures or the like, is excessively low or high, the polishing layer does not exhibit an appropriate hardness and elongation, and hence, in a polishing process to which the polishing pad is applied, the polishing layer may have an inappropriate physical and/or chemical effect on a polishing target, and thus the final polishing performance thereof may deteriorate.

[0083] The value determined by Equation 1 above may be 0.1 to 0.6, preferably 0.2 to 0.5. If the value determined by Equation 1 is excessively low, the hardness of the polishing layer may be excessively high or the elongation thereof may be excessively low, and thus the probability of occurrence of defects such as scratches on the surface of a polishing target layer during polishing may increase. In addition, if the value determined by Equation 1 is excessively high, a problem may arise that the removal rate does not reach a desired level. That is, when the value determined by Equation 1 is within the above range, the polishing layer may exhibit appropriate hardness and elongation, and based on these properties, the polishing layer may exhibit appropriate elasticity and physical properties for a polishing target layer during a polishing process, and thus may exhibit advantageous effects in terms of removal rate, pad cutting rate, defect prevention, and the like.

[0084] The polishing layer of the present disclosure has a tensile strength of 18 N/mm² to 22 N/mm², and a hardness (Shore D) of 35 to 55. Due to the physical/mechanical properties of the polishing layer, defects on a semiconductor substrate during a polishing process may decrease.

5 **[0085]** Specifically, when the polishing layer is depolymerized under the conditions described below and the molecular weights of the depolymerized composition are measured by GPC, the number-average molecular weight (Mn) of the depolymerized composition is 1,800 g/mol to 2,800 g/mol, preferably 2,000 g/mol to 2,500 g/mol, more preferably 2,100 g/mol to 2,350 g/mol. Furthermore, the weight-average molecular weight
10 (Mw) thereof is 2,000 g/mol to 3,000 g/mol, preferably 2,300 g/mol to 2,700 g/mol, more preferably 2,400 g/mol to 2,600 g/mol. The peak molecular weight (Mp) thereof is 2,000 g/mol to 3,000 g/mol, preferably 2,100 g/mol to 2,700 g/mol, more preferably 2,200 g/mol to 2,500 g/mol.

[0086] When the number-average molecular weight and weight-average molecular
15 weight values of the depolymerized composition are satisfied within the above ranges, the value of Equation 1 are satisfied. As the value of Equation 1 is satisfied, the polishing layer may have appropriate hardness and elongation, and as a result, may achieve a desired removal rate and defect reduction effect.

[0087] Specifically, the composition of the depolymerized polishing layer is
20 characterized by having a polydispersity index (PDI, Mw/Mn) of 1.2 or less. In general, as the measured polydispersity index of a polymer is closer to 1, it means that the molecular weight distribution of the polymer is broader. In general, when a cured polymer is decomposed by depolymerization, the positions where the bond of the cured polymer is broken under depolymerization conditions may be different, and thus the cured polymer
25 exists in a form in which various polymers are distributed.

[0088] On the other hand, the polishing layer of the present disclosure includes a cured product obtained by curing a polyurethane prepolymer, and the polydispersity index thereof is 1.2 or less as measured for a polymer in which the bond of the compound has been broken by depolymerization of the cured product, indicating that the polishing pad shows a monodisperse distribution. That is, the polishing layer of the present disclosure is characterized in that it is decomposed by depolymerization so as to have a narrow molecular weight distribution.

[0089] Specifically, the composition of the depolymerized polishing layer has a peak molecular weight(Mp) of 2,000 g/mol to 3,000 g/mol, preferably 2,100 g/mol to 2,700 g/mol, more preferably 2,200 g/mol to 2,500 g/mol., and a weight-average molecular weight (Mw) of 2,000 g/mol to 3,000 g/mol, preferably 2,300 g/mol to 2,700 g/mol, more preferably 2,400 g/mol to 2,600 g/mol.

[0090] In a conventional art, in order to apply a polishing pad to a CMP polishing process, it was necessary to check the average removal rate and the pad cutting rate through a direct polishing test on the polishing pad, and to examine whether the polishing pad could be applied.

[0091] This implies that it is necessary to check performance through a polishing test when selecting a polishing pad to be used in the polishing process, suggesting that a time- and cost-consuming procedure is essential.

[0092] On the contrary, according to the present disclosure, it is possible to select a polishing pad through measurement of the number-average molecular weight (Mn), weight-average molecular weight (Mw) and peak molecular weight (Mp) of the polishing layer using the GPC measurement result values thereof after depolymerization, and it is possible to select a polishing pad capable of reducing defects, which occur on the surface of a semiconductor substrate during a polishing process, by using the value of Equation 1

above.

[0093] This suggests that it is possible to predict the performance of the polishing pad even without performing a direct polishing test, thereby greatly simplifying the procedure for applying the polishing pad to the polishing process.

5 [0094] FIG. 1 schematically illustrates a section of a polishing pad according to an embodiment.

[0095] Referring to FIG. 1(a), a polishing pad 100 includes a polishing layer 10, and may include a cushion layer 20 on one surface of the polishing layer 10. The polishing layer 10 is in the form of a sheet having a predetermined thickness, and may include a first surface
10 11 functioning as a polishing surface coming into direct or indirect contact with the polishing target surface of a polishing target, and may include a second surface 12 opposite to the first surface 11.

[0096] In one embodiment, the first surface 11 may include grooves 13 machined to a depth less than the thickness of the polishing layer 10. The grooves 13 may have concentric
15 structures formed from the center of the polishing layer 10 toward the end thereof with respect to the planar structure of the first surface 11 so as to be spaced apart from each other at a predetermined distance. In another embodiment, the grooves 13 may have radial structures continuously formed from the center of the polishing layer 10 toward the end thereof with respect to the planar structure of the first surface 11. In still another
20 embodiment, the grooves 13 may have both the concentric structures and the radial structures. The grooves 13 may serve to control the fluidity of a polishing solution or polishing slurry that is supplied onto the first surface 11 during a polishing process that is performed using the polishing pad 100, or to control the polishing result by controlling the physical properties of the contact area between the polishing surface and the polishing
25 target surface.

[0097] In one embodiment, the thickness of the polishing layer 10 may be about 0.8 mm to about 5.0 mm, for example, about 1.0 mm to about 4.0 mm, for example, about 1.0 mm to 3.0 mm, for example, about 1.5 mm to about 3.0 mm, for example, about 1.7 mm to about 2.7 mm, for example, about 2.0 mm to about 3.5 mm.

5 **[0098]** The polishing layer 10 may have a porous structure including a plurality of pores. The average diameter of the plurality of pores may be, but is not limited to, about 5 μm to about 50 μm , for example, about 5 μm to about 40 μm , for example, about 10 μm to about 40 μm , for example, about 10 μm to about 35 μm .

10 **[0099]** The plurality of pores may appear as fine concave portions (not shown), a part of which is exposed to the outside from the polishing surface of the polishing layer and distinguished from the grooves 13. The plurality of pores together with the grooves may function as a control element for polishing properties by determining the fluidity and mooring space of the polishing liquid or polishing slurry during use of the polishing pad.

15 **[00100]** The polishing surface 11 may have a predetermined surface roughness due to the fine concave portions that are distinguished from the grooves 13. In one embodiment, the surface roughness (Ra) of the polishing surface 11 may be about 3 μm to about 1 mm. For example, the surface roughness (Ra) of the polishing surface 11 may be about 3 μm to about 20 μm , for example, about 3 μm to about 10 μm .

20 **[00101]** The cushion layer 20 is disposed on the second surface 12 of the polishing layer 10 and may serve to relieve the external pressure or impact transmitted to the polishing target surface during the polishing process while supporting the polishing layer 10. Thereby, the cushion layer 20 may contribute to preventing damage to the polishing target and defects thereon from occurring in the polishing process to which the polishing pad 100 is applied.

25 **[00102]** In one embodiment, the cushion layer 20 may have a thickness of about 0.5

mm to about 2.5 mm, for example, about 0.8 mm to about 2.5 mm, for example, about 1.0 mm to about 2.5 mm, about 1.0 mm to about 2.0 mm, for example, about 1.2 mm to about 1.8 mm.

5 **[00103]** Referring to FIG. 1 (b), in one embodiment, the polishing pad 200 includes the polishing layer 10 and the cushion layer 20, and may further include a first adhesive layer 30 disposed at the interface between the polishing layer 10 and the cushion layer 20. For example, the first adhesive layer 30 may be derived from a heat-sealing adhesive, but is not limited thereto.

10 **[00104]** The polishing pad 200 may further include a second adhesive layer 40 disposed on the second surface 12 of the polishing layer 10. The second adhesive layer 40 is a configuration for attaching the polishing pad to the surface plate of a polishing apparatus, and may be disposed directly on the second surface 12 of the polishing layer 10, or may be disposed on another layer such as the cushion layer 20 on the polishing layer 10, as shown in FIG. 1(b). For example, the second adhesive layer 40 may be derived from a
15 pressure sensitive adhesive, but is not limited thereto.

20 **[00105]** In one embodiment, the polishing pad may include a penetrating region penetrating the uppermost layer and the lowermost layer thereof. The penetrating region is a configuration for detecting a polishing end point during use of the polishing pad, and light having a predetermined wavelength may pass therethrough. In one embodiment, a light-transmitting window may be disposed in the penetrating region. The light-transmitting window may have a transmittance of more than about 30%, for example, about 40% to about 80%, for light having any one wavelength selected from wavelengths of about 500 nm to about 700 nm.

25 **[00106]** The polishing layer may include a cured product of a preliminary composition containing a urethane-based prepolymer. In one embodiment, the preliminary

composition may further contain a curing agent and a foaming agent. The term “prepolymer” refers to a polymer with a relatively low molecular weight, the polymerization of which has been stopped in an intermediate step in the production of a cured product so as to facilitate molding. The prepolymer itself may be subjected to an additional curing process such as heating and/or pressurization, or the prepolymer may be mixed and reacted with another polymerizable compound, for example, an additional compound such as a different kind of monomer or a different kind of prepolymer, and then molded into a final cured product.

[00107] In one embodiment, the urethane-based prepolymer may be produced by reacting an isocyanate compound with a polyol compound.

[00108] The isocyanate compound that is used in the production of the urethane-based prepolymer may be one selected from the group consisting of an aromatic diisocyanate, an aliphatic diisocyanate, an alicyclic diisocyanate, and combinations thereof. In one embodiment, the isocyanate compound may include an aromatic diisocyanate.

[00109] The isocyanate compound may include, for example, one selected from the group consisting of 2,4-toluenediisocyanate (2,4-TDI), 2,6-toluenediisocyanate (2,6-TDI), naphthalene-1,5-diisocyanate, p-phenylenediisocyanate, tolidinediisocyanate, 4,4'-diphenylmethanediisocyanate, hexamethylenediisocyanate, dicyclohexylmethanediisocyanate, 4,4'-dicyclohexylmethanediisocyanate (H₁₂MDI), isoporone diisocyanate, and combinations thereof.

[00110] The term “polyol” refers to a compound containing at least two hydroxyl groups (-OH) per molecule. In one embodiment, the polyol compound may include a dihydric alcohol compound having two hydroxyl groups, that is, a diol or a glycol.

[00111] The polyol compound may include, for example, one selected from the group consisting of polyether polyol, polyester polyol, polycarbonate polyol, acrylic polyol,

and combinations thereof.

[00112] The polyol compound may include, for example, one selected from the group consisting of polytetramethylene ether glycol (PTMG), polypropylene ether glycol, ethylene glycol, 1,2-propylene glycol, 1,3-propylene glycol, 1,2-butanediol, 1,3-butanediol, 2-methyl-1,3-propanediol, 1,4-butanediol, neopentyl glycol, 1,5-pentanediol, 3-methyl-1,5-pentanediol, 1,6-hexanediol, diethylene glycol (DEG), dipropylene glycol (DPG), tripropylene glycol, polypropylene glycol, and combinations thereof.

[00113] The polyol compound may have a weight-average molecular weight (Mw) of about 100 g/mol to about 3,000 g/mol. For example, the polyol compound may have a weight-average molecular weight (Mw) of from about 100 g/mol to about 3,000 g/mol, for example, about 100 g/mol to about 2,000 g/mol, for example, about 100 g/mol to about 1,800 g/mol.

[00114] In one embodiment, the polyol compound may include a low-molecular-weight polyol having a weight average molecular weight (Mw) of about 100 g/mol to less than about 300 g/mol, and a high-molecular-weight polyol having a weight-average molecular weight (Mw) of about 300 g/mol to about 1800 g/mol. In one embodiment, the high-molecular-weight polyol may include a first high-molecular-weight polyol having a weight-average molecular weight (Mw) of about 500 g/mol to about 800 g/mol, and a second high-molecular-weight polyol having a weight-average molecular weight (Mw) of greater than about 800 g/mol to less than or equal to about 1,800 g/mol. In this case, the polyol compound may form an appropriate cross-linked structure in the urethane-based prepolymer, and the polishing layer formed by curing the preliminary composition containing the urethane-based prepolymer under certain process conditions may more advantageously achieve the above-described effect. That is, the nuclear magnetic resonance (NMR) ^{13}C spectrum of the processed composition prepared by treating the

polishing layer under predetermined conditions may exhibit the above-described peak area ratio characteristics by the appropriate cross-linked structure of the polyol compound, and excellent polishing properties corresponding thereto may be achieved.

5 **[00115]** The urethane-based prepolymer may have a weight-average molecular weight (Mw) of about 500 g/mol to about 3,000 g/mol. The urethane-based prepolymer may have a weight-average molecular weight (Mw) of, for example, about 600 g/mol to about 2,000 g/mol, for example, about 800 g/mol to about 1,000 g/mol. When the urethane-based prepolymer has a degree of polymerization corresponding to the above-mentioned weight-average molecular weight (Mw), the polishing layer formed by curing the
10 preliminary composition under predetermined process conditions may more advantageously have a chemical bonding structure for achieving the above-described excellent polishing properties.

15 **[00116]** In one embodiment, the isocyanate compound for producing the urethane-based prepolymer may include an aromatic diisocyanate compound, and the aromatic diisocyanate compound may include, for example, 2,4-toluene diisocyanate (2,4-TDI) and 2,6-toluenediisocyanate (2,6-TDI). In addition, the polyol compound for producing the urethane-based prepolymer may include, for example, polytetramethylene ether glycol (PTMG) and diethylene glycol (DEG).

20 **[00117]** In another embodiment, the isocyanate compound for producing the urethane-based prepolymer may include an aromatic diisocyanate compound and an alicyclic diisocyanate compound. For example, the aromatic diisocyanate compound may include 2,4-toluene diisocyanate (2,4-TDI) and 2,6-toluene diisocyanate (2,6-TDI), and the alicyclic diisocyanate compound may include dicyclohexylmethanediisocyanate (H₁₂MDI). In addition, the polyol compound for producing the urethane-based prepolymer
25 may include, for example, polytetramethylene ether glycol (PTMG) and diethylene glycol

(DEG).

5 **[00118]** In the preliminary composition, the total amount of the polyol compound may be about 100 parts by weight to about 250 parts by weight, for example, about 120 parts by weight to about 250 parts by weight, for example, for example, about 120 parts by weight to about 240 parts by weight, for example, about 150 parts by weight to about 240 parts by weight, for example, about 190 parts by weight to about 240 parts by weight, based on 100 parts by weight of the total amount of the isocyanate compound among the total components for producing the urethane-based prepolymer.

10 **[00119]** In the preliminary composition, when the isocyanate compound for producing the urethane-based prepolymer includes the aromatic isocyanate compound and the aromatic isocyanate compound includes 2,4-TDI and 2,6-TDI, the content of 2,6-TDI may be about 1 part by weight to about 40 parts by weight, for example, about 1 part by weight to about 30 parts by weight, for example, about 3 parts by weight to about 28 parts by weight, for example, about 1 part by weight to about 10 parts by weight, based on 100 parts by weight of the 2,4-TDI.

15 **[00120]** In the preliminary composition, when the isocyanate compound for producing the urethane-based prepolymer includes the aromatic isocyanate compound and the alicyclic isocyanate compound, the content of the alicyclic isocyanate compound may be about 5 parts by weight to about 30 parts by weight, for example, about 10 parts by weight to about 25 parts by weight, based on 100 parts by weight of the total weight of the aromatic isocyanate compound.

20 **[00121]** The preliminary composition may have an isocyanate group content (NCO%) of about 5 wt% to about 11 wt%, for example, about 5 wt% to about 10 wt%, for example, about 5 wt% to about 8.5 wt%. The term “isocyanate group content” means the weight percentage of isocyanate groups (-NCO), which are present as free reactive groups

25

without being subjected to urethane reaction, relative to the total weight of the preliminary composition. The isocyanate group content (NCO%) of the preliminary composition may be designed by comprehensively controlling the types and contents of the isocyanate compound and polyol compound for producing the urethane-based prepolymer, process conditions such as the temperature, pressure and time of the process for producing the urethane-based prepolymer, and the types and contents of additives that are used in the production of the urethane-based prepolymer.

[00122] In one embodiment, the nuclear magnetic resonance (NMR) ^{13}C spectrum of the preliminary composition may show a fourth peak and a fifth peak in descending order of peak position (ppm) at 16 ppm to 20 ppm, and the area ratio of the fourth peak to the fifth peak may be about 1:1 to about 10:1.

[00123] Specifically, the nuclear magnetic resonance (NMR) ^{13}C spectrum of the preliminary composition may have a fourth peak in a range of 17.5 ppm to 20.0 ppm and a fifth peak in a range of 16 ppm to 17.5 ppm. For example, the area ratio of the fourth peak to the fifth peak may be about 1:1 to about 10:1, for example, about 3:1 to 10:1, for example, about 3.5:1 to about 9:1, for example about 3.5:1 to 8:1. The polishing layer formed by curing the preliminary composition having such peak characteristics under predetermined process conditions may more advantageously exhibit properties suitable for achieving desired levels of removal rate, polishing flatness, and defect reduction effect.

[00124] In one embodiment, the preliminary composition may have a weight-average molecular weight (M_w) of 3,800 to 4,700 as measured by GPC, a number-average molecular weight (M_n) of 2,800 to 3,500 as measured by GPC, and a peak molecular weight (M_p) of 3,500 to 4,500 as measured by GPC.

[00125] Specifically, the preliminary composition contains the urethane-based prepolymer, and the polishing layer formed by curing the preliminary composition, which

satisfies the characteristics of the ranges of the GPC measurement values, under predetermined process conditions, may more advantageously exhibit physical properties suitable for achieving desired levels of removal rate, polishing flatness, and defect reduction effect.

5 **[00126]** The preliminary composition is a composition containing the urethane-based prepolymer, and the chemical bonding structure in the cured structure of the polishing layer may vary depending on the chemical structure of the urethane-based prepolymer itself, and/or the concentrations of free functional groups contained in the urethane-based prepolymer and free reactive groups contained in the remaining unreacted
10 monomers. Meanwhile, even if the types or contents of the monomers constituting the urethane-based prepolymer and the remaining unreacted monomers are the same, the chemical bond structure in the cured structure of the polishing layer and the resulting nuclear magnetic resonance (NMR) ¹³C spectrum peak characteristics may vary depending on reaction process conditions for producing the urethane-based prepolymer, or curing
15 process conditions for producing the polishing layer; or processing conditions for preparing the processed composition.

[00127] As a view for explaining this, FIG. 3 is a schematic view illustrating an example of each of a preliminary composition 50, a cured structure 60 constituting the polishing layer, and a processed composition 70. Referring to FIG. 3, the preliminary
20 composition 50 is prepared by reacting monomer A, monomer B, monomer C, and monomer D, and may contain, for example, a first prepolymer (A-B-C-B-A) and a second prepolymer (A-B-C-B-D), and may include unreacted monomer D. When the types of monomers for preparing the preliminary composition 50 change, the chemical structure of the prepolymer will also change. In addition, even when the same monomers are used as
25 raw materials, the structure of the prepolymer and the type of unreacted monomer may

vary depending on reaction conditions such as temperature, pressure and time for preparing the preliminary composition 50. Subsequently, additive E is added to the preliminary composition 50, and then the cured structure 60 having a longer chain structure and cross-linked structure than the prepolymer is formed by curing under curing process conditions such as a predetermined temperature, pressure and time. The chemical structure of the cured structure 60 may also vary depending on the type of the additive and/or process conditions for producing the polishing layer. Then, the cured structure 60 is treated under condition 1 to obtain a processed composition 70. At least a portion of the bond structure of the cured structure 60 is broken and dissociated under condition 1, and thus a final processed composition 70 including structure 1 (A-B-C), structure 2 (B-A-E-D-A-B) and structure 3 (C-B-A) is obtained. In this case, processed compositions obtained by treatment under conditions other than condition 1 will include structures having chemical structures different from those of structures 1, 2 and 3 above.

[00128] That is, the peak characteristics of the nuclear magnetic resonance (NMR) ^{13}C spectrum of a processed composition obtained by treatment under conditions, under which 1 g of the polishing layer is added to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowed to react in a closed container at a temperature of 150°C for 48 hours, are characteristics comprehensively displayed by the organic relationship between the preliminary composition for producing the polishing layer, the types and contents of monomers for producing the urethane-based prepolymer of the preliminary composition, various process conditions in the processes for preparation of the preliminary composition and production of the polishing layer, and treatment conditions for obtaining the processed composition. However, the technical purpose of the polishing pad according to an embodiment is to reveal the correlation that the resultant polishing performance of the polishing pad is realized at a desired level when the peak characteristics of the nuclear

magnetic resonance (NMR) ^{13}C spectrum of the processed composition satisfies the above-mentioned conditions. As long as this purpose is satisfied, even the case in which slightly different types and contents of monomers, slightly different process conditions, etc. are applied cannot be regarded as departing from the scope of rights sought in the present disclosure.

[00129] In one embodiment, the isocyanate compound for producing the urethane-based prepolymer may include an aromatic diisocyanate compound, and the aromatic diisocyanate compound may include 2,4-toluene diisocyanate (2,4-TDI) and 2,6-toluenediisocyanate (2,6-TDI). In this case, the urethane-based prepolymer may include at least one of a first unit structure derived from 2,4-TDI subjected to urethane reaction at one end, a second unit structure derived from 2,6-TDI subjected to urethane reaction at one end, and a third unit structure derived from 2,4-TDI subjected to urethane reaction at both ends. As used herein, the expression “subjected to urethane reaction at one end” means that one of two isocyanate groups of a diisocyanate has been subjected to urethane reaction, and the expression “subjected to urethane reaction at both ends” means that two isocyanate groups of a diisocyanate have all been subjected to urethane reaction. In addition, the term “unit structure” refers to at least one structural unit included in the chemical structure of the main chain of the prepolymer.

[00130] In one embodiment, the urethane-based prepolymer may include a plurality of prepolymers having different repeating structures, and each of the prepolymers may independently include at least one of the first unit structure, the second unit structure and the third unit structure. Accordingly, the polishing layer including the cured product of the preliminary composition may more advantageously achieve a desired level of polishing performance.

[00131] As described above, the nuclear magnetic resonance (NMR) ^{13}C spectrum

peak characteristics of the preliminary composition may be comprehensively determined by the types and contents of monomers constituting the urethane-based prepolymer, the type and content of unreacted monomer remaining in addition to the urethane-based prepolymer, the chemical bond structure of the urethane-based prepolymer, reaction
5 process conditions for producing the urethane-based prepolymer, and the like.

[00132] The curing agent is a compound that chemically reacts with the urethane-based prepolymer to form a final cured structure in the polishing layer, and may include, for example, an amine compound or an alcohol compound. Specifically, the curing agent may include one selected from the group consisting of aromatic amines, aliphatic amines,
10 aromatic alcohols, aliphatic alcohols, and combinations thereof.

[00133] For example, the curing agent may include one selected from the group consisting of 4,4'-methylenebis(2-chloroaniline (MOCA), diethyltoluenediamine (DETDA), diaminodiphenylmethane, dimethyl thio-toluene diamine (DMTDA), propanediol bis-p-aminobenzoate, methylene bis-methylantranilate,
15 diaminodiphenylsulfone, m-xylylenediamine, isophoronediamine, ethylenediamine, diethylenetriamine, triethylenetetramine, polypropylenediamine, polypropylenetriamine, bis(4-amino-3-chlorophenyl)methane, and combinations thereof.

[00134] The content of the curing agent may be about 18 parts by weight to about 27 parts by weight, for example, about 19 parts by weight to about 26 parts by weight, for
20 example, about 20 parts by weight to about 26 parts by weight, based on 100 parts by weight of the preliminary composition. When the content of the curing agent satisfies the above range, it may more advantageously realize the desired performance of the polishing pad.

[00135] When the curing agent includes an amine compound, the molar ratio of
25 isocyanate (NCO) groups in the preliminary composition to amine (NH₂) groups in the

curing agent may be about 1:0.60 to about 1:0.99, for example, from about 1:0.60 to about 1:0.90, for example, about 1:0.60 to less than about 1:0.90.

5 **[00136]** The foaming agent is a component for forming a pore structure in the polishing layer, and may include one selected from the group consisting of a solid foaming agent, a gaseous foaming agent, a liquid foaming agent, and combinations thereof. In one embodiment, the foaming agent may include a solid foaming agent, a gaseous foaming agent, or a combination thereof.

10 **[00137]** The average particle diameter of the solid foaming agent may be about 5 μm to about 200 μm , for example, about 20 μm to about 50 μm , for example, about 21 μm to about 50 μm , for example, about 21 μm to about 40 μm .

15 **[00138]** When the solid foaming agent is thermally expanded particles as described below, the average particle diameter of the solid foaming agent means the average particle diameter of the thermally expanded particles themselves, and when the solid foaming agent is unexpanded particles as described below, the average particle diameter of the solid foaming agent may mean the average particle diameter of the solid foaming agent after being expanded by heat or pressure.

20 **[00139]** The solid foaming agent may include expandable particles. The expandable particles are particles having a property that can be expanded by heat or pressure, and the size thereof in the final polishing layer may be determined by the heat or pressure applied during the process of producing the polishing layer. The expandable particles may include thermally expanded particles, unexpanded particles, or a combination thereof. The thermally expanded particles are particles pre-expanded by heat, and refer to particles having little or no size change caused by the heat or pressure applied during the process of producing the polishing layer.

25 **[00140]** The unexpanded particles are non-pre-expanded particles, and refer to

particles whose final size is determined by expansion caused by the heat or pressure applied during the process of producing the polishing layer.

[00141] The expandable particles may include: an outer shell made of a resin material; and an expansion-inducing component enclosed by and present in the outer shell.

5 [00142] For example, the outer shell may include a thermoplastic resin, and the thermoplastic resin may be at least one selected from the group consisting of a vinylidene chloride-based copolymer, an acrylonitrile-based copolymer, a methacrylonitrile-based copolymer, and an acrylic copolymer.

10 [00143] The expansion-inducing component may include one selected from the group consisting of a hydrocarbon compound, a chlorofluoro compound, a tetraalkylsilane compound, and combinations thereof.

[00144] Specifically, the hydrocarbon compound may include one selected from the group consisting of ethane, ethylene, propane, propene, n-butane, isobutane, n-butene, isobutene, n-pentane, isopentane, neopentane, n-hexane, heptane, petroleum ether, and combinations thereof.

15 [00145] The chlorofluoro compound may include one selected from the group consisting of trichlorofluoromethane (CCl_3F), dichlorodifluoromethane (CCl_2F_2), chlorotrifluoromethane (CClF_3), tetrafluoroethylene ($\text{CClF}_2\text{-CClF}_2$), and combinations thereof.

20 [00146] The tetraalkylsilane compound may include one selected from the group consisting of tetramethylsilane, trimethylethylsilane, trimethylisopropylsilane, trimethyl-n-propylsilane, and combinations thereof.

[00147] The solid foaming agent may optionally include particles treated with an inorganic component. For example, the solid foaming agent may include expandable particles treated with an inorganic component. In one embodiment, the solid foaming agent

may include expandable particles treated with silica (SiO₂) particles. The treatment of the solid foaming agent with the inorganic component may prevent aggregation between a plurality of particles. The chemical, electrical, and/or physical properties of the surface of the inorganic component-treated solid foaming agent may differ from those of a solid foaming agent not treated with the inorganic component.

[00148] The content of the solid foaming agent may be about 0.5 parts by weight to about 10 parts by weight, for example, about 1 part by weight to about 3 parts by weight, for example, about 1.3 parts by weight to about 2.7 parts by weight, for example, about 1.3 parts by weight to about 2.6 parts by weight, based on 100 parts by weight of the urethane-based prepolymer.

[00149] The type and content of the solid foaming agent may be designed depending on the desired pore structure and physical properties of the polishing layer.

[00150] The gaseous foaming agent may include an inert gas. The gaseous foaming agent may be used as a pore-forming element which is added during a reaction between the urethane-based prepolymer and the curing agent.

[00151] The type of inert gas is not particularly limited as long as it does not participate in the reaction between the urethane-based prepolymer and the curing agent. For example, the inert gas may include one selected from the group consisting of nitrogen gas (N₂), argon gas (Ar), helium gas (He), and combinations thereof. Specifically, the inert gas may include nitrogen gas (N₂) or argon gas (Ar).

[00152] The type and content of the gaseous foaming agent may be designed depending on the desired pore structure and physical properties of the polishing layer.

[00153] In one embodiment, the foaming agent may include a solid foaming agent. For example, the foaming agent may consist only of a solid foaming agent.

[00154] The solid foaming agent may include expandable particles, and the

expandable particles may include thermally expanded particles. For example, the solid foaming agent may consist only of thermally expanded particles. When the solid foaming agent consists only of the thermally expanded particles without including the unexpanded particles, the variability of the pore structure may be lowered, but the possibility of predicting the pore structure may increase, and thus the solid foaming agent may advantageously achieve homogeneous pore properties throughout the polishing layer.

[00155] In one embodiment, the thermally expanded particles may be particles having an average particle diameter of about 5 μm to about 200 μm . The average particle diameter of the thermally expanded particles may be about 5 μm to about 100 μm , for example, about 10 μm to about 80 μm , for example, about 20 μm to about 70 μm , for example, about 20 μm to about 50 μm , for example, about 30 μm to about 70 μm , for example, about 25 μm to 45 μm , for example, about 40 μm to about 70 μm , for example, about 40 μm to about 60 μm . The average particle diameter is defined as the D50 of the thermally expanded particles.

[00156] In one embodiment, the density of the thermally expanded particles may be about 30 kg/m^3 to about 80 kg/m^3 , for example, about 35 kg/m^3 to about 80 kg/m^3 , for example, about 35 kg/m^3 to about 75 kg/m^3 , for example about 38 kg/m^3 to about 72 kg/m^3 , for example, about 40 kg/m^3 to about 75 kg/m^3 , for example, 40 kg/m^3 to about 72 kg/m^3 .

[00157] In one embodiment, the foaming agent may include a gaseous foaming agent. For example, the foaming agent may include a solid foaming agent and a gaseous foaming agent. Details regarding the solid foaming agent are as described above.

[00158] The gaseous foaming agent may include nitrogen gas.

[00159] The gaseous foaming agent may be injected through a predetermined injection line during the process in which the urethane-based prepolymer, the solid foaming agent and the curing agent are mixed together. The injection rate of the gaseous

foaming agent may be about 0.8 L/min to about 2.0 L/min, for example, about 0.8 L/min to about 1.8 L/min, for example, about 0.8 L/min to about 1.7 L/min, for example, about 1.0 L/min to about 2.0 L/min, for example, about 1.0 L/min to about 1.8 L/min, for example, about 1.0 L/min to about 1.7 L/min.

5 **[00160]** The composition for producing the polishing layer may further contain other additives such as a surfactant and a reaction rate controller. The names such as “surfactant” and “reaction rate controller” are arbitrary names given based on the main function of the corresponding substance, and each corresponding substance does not necessarily perform only a function limited to the function indicated by the corresponding
10 name.

[00161] The surfactant is not particularly limited as long as it is a material that serves to prevent aggregation or overlapping of pores. For example, the surfactant may include a silicone-based surfactant.

[00162] The surfactant may be used in an amount of about 0.2 parts by weight to
15 about 2 parts by weight based on 100 parts by weight of the urethane-based prepolymer. Specifically, the surfactant may be contained in an amount of about 0.2 parts by weight to about 1.9 parts by weight, for example, about 0.2 parts by weight to about 1.8 parts by weight, for example, about 0.2 parts by weight to about 1.7 parts by weight, for example, about 0.2 parts by weight to about 1.6 parts by weight, for example, about 0.2 parts by
20 weight to about 1.5 parts by weight, for example, about 0.5 parts by weight to 1.5 parts by weight, based on 100 parts by weight of the urethane-based prepolymer. When the surfactant is contained in an amount within the above range, pores derived from the gaseous foaming agent may be stably formed and maintained in the mold.

[00163] The reaction rate controller serves to accelerate or retard the reaction, and
25 depending on the purpose thereof, may include a reaction accelerator, a reaction retarder,

or both. The reaction rate controller may include a reaction accelerator. For example, the reaction accelerator may be at least one reaction accelerator selected from the group consisting of a tertiary amine-based compound and an organometallic compound.

[00164] Specifically, the reaction rate controller may include at least one selected from the group consisting of triethylenediamine, dimethylethanolamine, tetramethylbutanediamine, 2-methyl-triethylenediamine, dimethylcyclohexylamine, triethylamine, triisopropanolamine, 1,4-diazabicyclo(2,2,2)octane, bis(2-methylaminoethyl)ether, trimethylaminoethylethanolamine, N,N,N,N,N"-pentamethyldiethylenetriamine, dimethylaminoethylamine, dimethylaminopropylamine, benzyldimethylamine, N-ethylmorpholine, N,N-dimethylaminoethylmorpholine, N,N-dimethylcyclohexylamine, 2-methyl-2-azanorbornene, dibutyltin dilaurate, stannous octoate, dibutyltin diacetate, dioctyltin diacetate, dibutyltin maleate, dibutyltin di-2-ethylhexanoate, and dibutyltin dimercaptide. Specifically, the reaction rate controller may include at least one selected from the group consisting of benzyldimethylamine, N,N-dimethylcyclohexylamine, and triethylamine.

[00165] The reaction rate controller may be used in an amount of about 0.05 parts by weight to about 2 parts by weight based on 100 parts by weight of the urethane-based prepolymer. Specifically, the reaction rate controller may be used in an amount of about 0.05 parts by weight to about 1.8 parts by weight, for example, about 0.05 parts by weight to about 1.7 parts by weight, for example, about 0.05 parts by weight to about 1.6 parts by weight, for example, about 0.1 parts by weight to about 1.5 parts by weight. parts, for example, about 0.1 parts by weight to about 0.3 parts by weight, for example, about 0.2 parts by weight to about 1.8 parts by weight, for example, about 0.2 parts by weight to about 1.7 parts by weight, for example, about 0.2 parts by weight to about 1.6 parts by weight, for example, about 0.2 parts by weight to about 1.5 parts by weight, for example,

about 0.5 parts by weight to about 1 part by weight, based on 100 parts by weight of the urethane-based prepolymer. When the reaction rate controlling agent is used in an amount within the above-described content range, it is possible to appropriately control the curing reaction rate of the preliminary composition to form a polishing layer having pores of a
5 desired size and a desired hardness.

[00166] When the polishing pad includes a cushion layer, the cushion layer may serve to absorb and disperse an external impact applied to the polishing layer while supporting the polishing layer, thereby minimizing the occurrence of damage to the polishing target and defects thereon during the polishing process performed using the
10 polishing pad.

[00167] The cushion layer may include, but is not limited to, non-woven fabric or suede.

[00168] In one embodiment, the cushion layer may be a resin-impregnated nonwoven fabric. The nonwoven fabric may be a fiber nonwoven fabric including one
15 selected from the group consisting of polyester fibers, polyamide fibers, polypropylene fibers, polyethylene fibers, and combinations thereof.

[00169] The resin impregnated into the nonwoven fabric may include one selected from the group consisting of polyurethane resin, polybutadiene resin, styrene-butadiene copolymer resin, styrene-butadiene-styrene copolymer resin, acrylonitrile-butadiene
20 copolymer resin, styrene-ethylene-butadiene-styrene copolymer resin, silicone rubber resin, polyester-based elastomer resin, polyamide-based elastomer resin, and combinations thereof.

[00170] In the polishing pad according to one embodiment, the hardness (Shore D) of the polishing surface of the polishing layer may be less than about 55, for example,
25 about 35 to less than about 50, for example, about 40 to 49. The tensile strength of the

polishing layer may be less than about 22 N/mm², for example, about 10 N/mm² to less than about 22N/mm², for example, about 18 N/mm² to about 20 N/mm². The elongation of the polishing layer may be about 200% or more, for example, about 200% to about 300%. The cutting rate of the polishing layer may be about 80 μm/hr or more, for example, about 80 μm/hr to about 100 μm/hr, for example, about 80 μm/hr to about 95 μm/hr. For example, when the hardness of the polishing surface, the tensile strength and elongation of the polishing layer, and the cutting rate of the polishing layer are simultaneously within the above-described ranges, the polishing layer may be evaluated as exhibiting physical and mechanical properties corresponding to the peak characteristics of the processed composition. In this case, the polishing pad including the polishing layer may be applied to a semiconductor device process and realize excellent polishing performance.

[00171] Hereinafter, a method for producing the polishing pad will be described.

[00172] In another embodiment of the present disclosure, there may be provided a method for producing a polishing pad, the method including steps of: preparing a preliminary composition containing a prepolymer; preparing a composition for producing a polishing layer containing the preliminary composition, a foaming agent and a curing agent; and producing a polishing layer by curing the composition for producing a polishing layer.

[00173] The step of preparing the preliminary composition may be a process of producing a urethane-based prepolymer by reacting a diisocyanate compound and a polyol compound. Details regarding the diisocyanate compound and the polyol compound are as described above with respect to the polishing pad.

[00174] The isocyanate group content (NCO%) of the preliminary composition may be about 5 wt% to about 11 wt%, for example from about 5 wt% to about 10 wt%, for example, about 5 wt% to about 8.5 wt%. In this case, the polishing layer having the above-

described chemical bond structure may be more advantageously obtained. The isocyanate group content of the preliminary composition may be derived from the terminal isocyanate groups of the urethane-based prepolymer, the unreacted unreacted isocyanate groups in the diisocyanate compound, and the like.

5 **[00175]** The viscosity of the preliminary composition may be about 100 cps to about 1,000 cps, for example, about 200 cps to about 800 cps, for example, about 200 cps to about 600 cps, for example, about 200 cps to about 550 cps, for example, about 300 cps to about 500 cps, at about 80°C.

10 **[00176]** The foaming agent may include a solid foaming agent or a gaseous foaming agent. Details regarding the type of foaming agent and the like are as described above with respect to the polishing pad.

15 **[00177]** When the foaming agent includes a solid foaming agent, the step of preparing the composition for producing a polishing layer may include steps of: preparing a first preliminary composition by mixing the preliminary composition and the solid foaming agent; and preparing a second preliminary composition by mixing the first preliminary composition and a curing agent.

20 **[00178]** The viscosity of the first preliminary composition may be about 1,000 cps to about 2,000 cps, for example, about 1,000 cps to about 1,800 cps, for example, about 1,000 cps to about 1,600 cps, for example, about 1,000 cps to about 1,500 cps, at about 80°C.

25 **[00179]** When the foaming agent includes a gaseous foaming agent, the step of preparing the composition for producing a polishing layer may include steps of: preparing a third preliminary composition containing the preliminary composition and the curing agent; and preparing a fourth preliminary composition by injecting the gaseous foaming agent into the third preliminary composition.

[00180] In one embodiment, the third preliminary composition may further contain a solid foaming agent.

[00181] In one embodiment, the process of producing a polishing layer may include steps of: preparing a mold preheated to a first temperature; and injecting and curing the composition for producing a polishing layer into the preheated mold; and post-curing the cured composition for producing a polishing layer at a second temperature higher than the preheating temperature.

[00182] In one embodiment, the temperature difference between the first temperature and the second temperature may be about 10°C to about 40°C, for example, about 10°C to about 35°C, for example, about 15°C to about 35°C.

[00183] In one embodiment, the first temperature may be about 60°C to about 100°C, for example, about 65°C to about 95°C, for example, about 70°C to about 90°C.

[00184] In one embodiment, the second temperature may be about 100°C to about 130°C, for example, about 100°C to 125°C, for example, about 100°C to about 120°C.

[00185] The step of curing the composition for producing a polishing layer at the first temperature may be performed for about 5 minutes to about 60 minutes, for example, about 5 minutes to about 40 minutes, for example, about 5 minutes to about 30 minutes, for example, about 5 minutes to about 25 minutes.

[00186] The step of post-curing the composition (cured at the first temperature) for producing a polishing layer at the second temperature may be performed for about 5 hours to about 30 hours, for example, about 5 hours to about 25 hours, for example, about 10 hours to about 30 hours, for example, about 10 hours to about 25 hours, for example, about 12 hours to about 24 hours, for example, about 15 hours to about 24 hours.

[00187] The polishing layer finally produced through the process of producing a polishing layer may be characterized in that the nuclear magnetic resonance (NMR) ¹³C

spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak is about 5:1 to about 10:1.

[00188] For example, the area ratio of the third peak to the second peak may be about 5:1 to about 10:1, for example, about 5:1 to about 8:1.

[00189] In one embodiment, the processing composition has an area ratio of the first peak to the second peak of 10:1 to 10:5, and an area ratio of the first peak to the third peak of 10:5 to 10:10. For example, the area ratio of the first peak to the second peak may be about 10:1 to about 10:5, for example, about 10:1.00 to about 10:1.60, for example, about 10:1.00 to about 10:1.60, for example, about 10:1.80 to 10:2.50, for example, greater than about 10:1.80 to less than or equal to about 10:2.50. For example, the area ratio of the first peak to the third peak may be 10:5 to 10:10, for example, greater than about 10:5.00 to less than or equal to about 10:10.00.

[00190] The method of producing a polishing pad may include a step of processing at least one surface of the polishing layer.

[00191] The step of processing at least one surface of the polishing layer may include at least one of steps of: (1) forming grooves on at least one surface of the polishing layer; (2) line-turning at least one surface of the polishing layer; and (3) roughening at least one surface of the polishing layer.

[00192] In step (1), the grooves may include at least one of concentric grooves formed from the center of the polishing layer so as to be spaced apart from each other at a predetermined distance, and radial grooves continuously connected from the center of the

polishing layer to the edge of the polishing layer.

[00193] In step (2), the line turning may be performed by a method of cutting the polishing layer by a predetermined thickness by means of a cutting tool.

[00194] The roughening in step (3) may be performed by a method of processing
5 the surface of the polishing layer with sanding rollers.

[00195] The method of producing a polishing pad may further include a step of laminating a cushion layer on a surface opposite to the polishing surface of the polishing layer. Details regarding the cushion layer are as described above with respect to the polishing pad.

10 **[00196]** The polishing layer and the cushion layer may be laminated to each other through a heat-sealing adhesive.

[00197] The heat-sealing adhesive may be applied onto a surface opposite to the polishing surface of the polishing layer, and the heat-sealing adhesive may be applied onto the surface to be in contact with the polishing layer of the cushion layer. The polishing
15 layer and the cushion layer may be laminated to each other in such a manner that the surfaces to which the heat-sealing adhesive has been applied come into contact with each other, and then the two layers may be laminated to each other using a pressure roller.

[00198] In another embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, the method including steps of: providing a
20 polishing pad including a polishing layer; and placing the polishing target surface of a polishing target so as to be in contact with the polishing surface of the polishing layer and then polishing the polishing target while rotating relative to each other, wherein the polishing target includes a semiconductor substrate, the nuclear magnetic resonance (NMR)
¹³C spectrum of a processed composition prepared by adding 1 g of the polishing layer to
25 a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react

in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak is about 5:1 to about 10:1.

5 **[00199]** Details regarding the polishing layer and the processed composition thereof are the same as those described above with respect to the polishing pad. When the polishing pad including the polishing layer having the above-described characteristics is applied in the method for fabricating a semiconductor device, the semiconductor device fabricated through this method may achieve excellent functions derived from excellent polishing
10 results of the semiconductor substrate.

[00200] In another embodiment of the present disclosure, there is provided a method for fabricating a semiconductor device, wherein the polishing layer may have a value of 0.1 to 0.6 as calculated according to Equation 1 below:

[00201] [Equation 1]

15 **[00202]**
$$\frac{M_p - M_n}{M_w - M_n}$$

[00203] wherein Mw, Mn and Mp are molecular weights measured by gel permeation chromatography (GPC) for a depolymerized composition prepared by adding 1 g of the polishing layer to 15 ml of a 0.3 M aqueous solution of KOH and depolymerizing the polishing layer in a closed container at 150°C for 48 hours,

20 **[00204]** Mw is the weight-average molecular weight of the depolymerized composition,

[00205] Mn is the number-average molecular weight of the depolymerized composition, and

[00206] Mp is the peak molecular weight of the depolymerized composition.

5 [00207] Details regarding the polishing layer and the processed composition thereof are the same as those described above with respect to the polishing pad. When the polishing pad including the polishing layer having the above-described characteristics is applied in the method for fabricating a semiconductor device, the semiconductor device fabricated through this method may achieve excellent functions derived from excellent polishing results of the semiconductor substrate.

10 [00208] FIG. 2 schematically illustrates a process drawing of a method for fabricating a semiconductor device according to an embodiment. Referring to FIG. 2, in the step of providing the polishing pad including the polishing layer, the polishing pad 110 may be disposed and provided on a surface plate 120.

15 [00209] The polishing target may include a semiconductor substrate, and the semiconductor substrate 130 may be disposed such that a polishing target surface thereof is in contact with the polishing surface of the polishing layer of the polishing pad 110. In this case, the polishing target surface of the semiconductor substrate 130 and the polishing surface of the polishing layer may come into direct contact with each other or come into indirect contact through a flowable slurry or the like.

20 [00210] In one embodiment, the method for fabricating a semiconductor device may further include a step of supplying a polishing slurry 150 onto the polishing surface of the polishing layer of the polishing pad 110. For example, the polishing slurry 150 may be supplied onto the polishing surface through a supply nozzle 140.

[00211] The flow rate of the polishing slurry 150 that is sprayed through the supply nozzle 140 may be about 10 ml/min to about 1,000 ml/min, for example, about 10 ml/min to about 800 ml/min, for example, from about 50 ml/min to about 500 ml/min, but is not limited thereto.

25 [00212] The polishing slurry 150 may include a silica slurry or a ceria slurry.

[00213] The semiconductor substrate 130 may come into contact with the polishing surface by pressing with a predetermined load in a state in which it is supported by a polishing head 160. For example, the load under which the polishing target surface of the semiconductor substrate 130 is pressed onto the polishing surface by the polishing head 160 may be selected within the range of, for example, about 0.01 psi to about 20 psi according to the purpose, and may be, for example, about 0.1 psi to about 15 psi, but is not limited thereto. When the polishing surface of the polishing layer and the polishing target surface of the semiconductor substrate are brought into contact with each other by the above-described load, the polishing layer may exhibit hardness and elongation represented by the above-described peak characteristics, and the elasticity and contact area corresponding thereto may be provided to the polishing target surface of the semiconductor substrate, and accordingly, the removal rate of the semiconductor substrate and the defect prevention effect may be advantageously realized at desired levels.

[00214] The semiconductor substrate 130 and the polishing pad 110 may be rotated relative to each other in a state in which the polishing target surface and the polishing surface are in contact with each other. In this case, the rotating direction of the semiconductor substrate 130 and the rotating direction of the polishing pad 110 may be the same direction or may be opposite to each other. The rotating speed of each of the semiconductor substrate 130 and the polishing pad 110 may be selected within the range of about 10 rpm to about 500 rpm depending on the purpose, and may be, for example, about 30 rpm to about 200 rpm, but is not limited thereto.

[00215] When the rotating speed of each of the semiconductor substrate and the polishing pad satisfies the above range, the polishing layer may exhibit hardness and elongation represented by the above-described peak characteristics, and the elasticity and contact area corresponding thereto may be provided to the polishing target surface of the

semiconductor substrate, and accordingly, the removal rate of the semiconductor substrate and the defect prevention effect may be advantageously realized at desired levels.

[00216] In one embodiment, the method for fabricating a semiconductor device may further include a step of processing the polishing surface of the polishing pad 110 by a conditioner 170 at the same time as polishing of the semiconductor substrate 130 in order to maintain the polishing surface of the polishing pad 110 in a state suitable for polishing.

[00217] In one embodiment, in the method for fabricating a semiconductor device, the semiconductor substrate may include a silicon dioxide (SiO_2) layer, the polishing target surface may be the surface of the silicon dioxide (SiO_2) layer, the number of surface defects on the polishing target surface after completion of the polishing may be less than 5, and the average removal rate of the silicon dioxide (SiO_2) layer is 1,500 Å/min to 2,500 Å/min, for example, about 1,500 Å/min to less than 2,500 Å/min.

[00218] The method for fabricating a semiconductor device may realize the above-described removal rate and defect prevention performance on a semiconductor substrate having a silicon dioxide (SiO_2) layer as a polishing target by applying the polishing pad including the polishing layer having the above-described characteristics.

[00219] Hereinafter, specific embodiments of the present disclosure will be presented. However, the examples described below serve merely to illustrate or explain the present disclosure in detail, and the scope of the present disclosure should not be limited thereto.

[00220] Example 1

[00221] 2,4-TDI and 2,6-TDI were mixed together at the relative weight ratios described in Table 1 below, based on 100 parts by weight of the total weight of the diisocyanate component. PTMG and DEG were mixed together at the relative weight ratio described in Table 1 below, based on 100 parts by weight of the total weight of the polyol

component. A raw material mixture was prepared by mixing 220 parts by weight of the total amount of the polyol with 100 parts by weight of the total amount of the diisocyanate. A preliminary composition containing a urethane-based prepolymer was prepared by placing the raw material mixture in a four-neck flask and then allowing the mixture to react at 80°C. The content of isocyanate groups (NCO groups) in the preliminary composition was adjusted to 6 wt%. 4,4'-methylenebis(2-chloroaniline) (MOCA) as a curing agent was added to the preliminary composition so that the molar ratio of the NH₂ groups of the MOCA to the NCO groups in the preliminary composition was 0.75. In addition, 1.0 part by weight of a solid foaming agent (Akzonobel Corp.) as expandable particles was added to the preliminary composition. The preliminary composition was injected into a mold, having a width of 1,000 mm, a length of 1,000 mm and a height of 3 mm and preheated to 90°C, at a discharge rate of 10 kg/min. Then, a polishing layer was produced by subjecting the preliminary composition to a post-curing reaction at a temperature of 110°C.

[00222] Example 2

[00223] 2,4-TDI, 2,6-TDI and H₁₂MDI were mixed together at the relative weight ratios described in Table 1 below, based on 100 parts by weight of the total weight of the diisocyanate component. PTMG and DEG were mixed together at the relative weight ratio described in Table 1 below, based on 100 parts by weight of the total weight of the polyol component. A raw material mixture was prepared by mixing 220 parts by weight of the total amount of the polyol with 100 parts by weight of the total amount of the diisocyanate. A preliminary composition containing a urethane-based prepolymer was prepared by placing the raw material mixture in a four-neck flask and then allowing the mixture to react at 80°C. The content of isocyanate groups (NCO groups) in the preliminary composition was adjusted to 8.0 wt%. 4,4'-methylenebis(2-chloroaniline) (MOCA) as a curing agent was added to the preliminary composition so that the molar ratio of the NH₂ groups of the

MOCA to the NCO groups in the preliminary composition was 0.70. In addition, 1.0 part by weight of a solid foaming agent (Akzonobel Corp.) as expandable particles was added to the preliminary composition. The preliminary composition was injected into a mold, having a width of 1,000 mm, a length of 1,000 mm and a height of 3 mm and preheated to 100°C, at a discharge rate of 10 kg/min. Then, a polishing layer was produced by subjecting the preliminary composition to a post-curing reaction at a temperature of 110°C.

[00224] Comparative Example 1

[00225] 2,4-TDI, 2,6-TDI and H₁₂MDI were mixed together at the relative weight ratios described in Table 1 below, based on 100 parts by weight of the total weight of the diisocyanate component. PTMG and DEG were mixed together at the relative weight ratio described in Table 1 below, based on 100 parts by weight of the total weight of the polyol component. A raw material mixture was prepared by mixing 150 parts by weight of the total amount of the polyol with 100 parts by weight of the total amount of the diisocyanate. A preliminary composition containing a urethane-based prepolymer was prepared by placing the raw material mixture in a four-neck flask and then allowing the mixture to react at 80°C. The content of isocyanate groups (NCO groups) in the preliminary composition was adjusted to 9 wt%. 4,4'-methylenebis(2-chloroaniline) (MOCA) as a curing agent was added to the preliminary composition so that the molar ratio of the NH₂ groups of the MOCA to the NCO groups in the preliminary composition was 0.96. In addition, 1.0 part by weight of a solid foaming agent (Akzonobel Corp.) as expandable particles was added to the preliminary composition. The preliminary composition was injected into a mold, having a width of 1,000 mm, a length of 1,000 mm and a height of 3 mm and preheated to 90°C, at a discharge rate of 10 kg/min, and at the same time, nitrogen (N₂) gas as a gaseous foaming agent was injected at an injection rate of 1.0 L/min for the same time as the injection time of the preliminary composition. Then, a polishing layer was produced by

subjecting the preliminary composition to a post-curing reaction at a temperature of 110°C.

[00226] Comparative Example 2

[00227] 2,4-TDI, 2,6-TDI and H₁₂MDI were mixed together at the relative weight ratios described in Table 1 below, based on 100 parts by weight of the total weight of the diisocyanate component. PTMG and DEG were mixed together at the relative weight ratio described in Table 1 below, based on 100 parts by weight of the total weight of the polyol component. A raw material mixture was prepared by mixing 150 parts by weight of the total amount of the polyol with 100 parts by weight of the total amount of the diisocyanate. A preliminary composition containing a urethane-based prepolymer was prepared by placing the raw material mixture in a four-neck flask and then allowing the mixture to react at 80°C. The content of isocyanate groups (NCO groups) in the preliminary composition was adjusted to 9.2 wt%. 4,4'-methylenebis(2-chloroaniline) (MOCA) as a curing agent was added to the preliminary composition so that the molar ratio of the NH₂ groups of the MOCA to the NCO groups in the preliminary composition was 0.94. In addition, 1.0 part by weight of a solid foaming agent (Akzonobel Corp.) as expandable particles was added to the preliminary composition. The preliminary composition was injected into a mold, having a width of 1,000 mm, a length of 1,000 mm and a height of 3 mm and preheated to 95°C, at a discharge rate of 10 kg/min. Then, a polishing layer was produced by subjecting the preliminary composition to a post-curing reaction at a temperature of 110°C.

[00228] Each of the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2 was processed to a thickness of 2 mm, and subjected to a process of machining grooves having a concentric shape on the polishing surface thereof. Next, a 1.1-mm-thick cushion layer including a urethane-based resin impregnated into a polyester resin nonwoven fabric was prepared, and a heat-sealing adhesive was applied to a surface opposite to the polishing surface and to the attachment surface of the cushion layer, and

laminated to each other using a pressure roller. As a result, final polishing pads were produced.

[00229] Experimental Example 1: Nuclear Magnetic Resonance (NMR) ^{13}C Spectra of Preliminary Compositions

5 **[00230]** For each of the preliminary compositions of Examples 1 and 2 and Comparative Examples 1 and 2, 5 mg of the preliminary composition was dissolved in CDCl_3 and ^{13}C -NMR analysis thereof was performed using a nuclear magnetic resonance (NMR) apparatus (JEOL 500 MHz, 90° pulse) at room temperature.

10 **[00231]** Pulse NMR measurements were made under the following conditions: a pulse width of 90° pulse, 2.0 μs , a repetition time of 2 seconds, a number of scans of 5,100, and a measurement temperature of room temperature (RT) (25°C).

[00232] Experimental Example 2: Nuclear Magnetic Resonance (NMR) ^{13}C Spectra of Processed Compositions

15 **[00233]** For each of the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2, 1 g of the polishing layer was added to 15 ml of a 0.3 M aqueous solution of sodium hydroxide (KOH) and allowed to react in a closed container having a volume of 48 ml at a temperature 150°C for 48 hours, thus preparing a processed composition. 5 mg of the processed composition was dissolved in CDCl_3 , and ^{13}C -NMR analysis thereof was performed using a nuclear magnetic resonance (NMR) apparatus (JEOL 500MHz, 90° pulse) at room temperature.

20 **[00234]** Experimental Example 3: Evaluation of Physical Properties of Polishing Layer or Polishing Pad

[00235] (1) Hardness

25 **[00236]** Each of the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2 was processed to a thickness of 2 mm, and then cut to a size of 5 cm

(width) x 5 cm (length), thus preparing samples. After each of the samples was stored at a temperature of 25°C for 12 hours, and then the Shore D hardness thereof was measured using a durometer.

[00237] (2) Tensile Strength

5 **[00238]** Each of the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2 was processed to a thickness of 2 mm, and then cut to a size of 4 cm (width) x 1 cm (length), thus preparing samples. For each of the samples, the maximum strength value immediately before breaking was measured using a universal testing machine (UTM) at a speed of 50 mm/min.

10 **[00239]** (3) Elongation

[00240] Each of the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2 was processed to a thickness of 2 mm, and then cut to a size of 4 cm (width) x 1 cm (length), thus preparing samples. For each of the samples, the maximum deformed length immediately before breaking was measured using a universal testing machine (UTM) at a speed of 50 mm/min, and then the ratio of the maximum deformed length to the initial length was expressed as a percentage (%).

[00241] (4) Cutting Rate

[00242] For each polishing pad produced as described above using each of the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2, the polishing pad was pre-conditioned with deionized water for 10 minutes, and then conditioned while spraying deionized water thereto for 1 hour. The thickness that changed in the conditioning process was measured, and then the thickness change ($\mu\text{m/hr}$) was calculated as the cutting rate of the polishing pad. The system used for conditioning was AP-300HM (CTS Co., Ltd.), the conditioning pressure was 6 lbf, the rotating speed was 100 to 110 rpm, and the disk used for conditioning was CI-45 (Sasol Co., Ltd.).

[00243] Experimental Example 4: Evaluation of Polishing Performance

[00244] After polishing pads to which the polishing layers of Examples 1 and 2 and Comparative Examples 1 and 2 were applied, respectively, were produced, the polishing performance thereof was evaluated as follows.

5 **[00245]** Silicon dioxide (SiO₂) was deposited on a silicon wafer having a diameter of 300 mm by a chemical vapor deposition (CVD) process. Each of the polishing pads was attached to a CMP machine, and the silicon wafer was mounted such that the surface of the silicon dioxide layer on the silicon wafer faced the polishing surface of the polishing pad. While a calcined ceria slurry was supplied onto the polishing pad at a rate of 250
10 mL/min, the silicon wafer was pressed onto the polishing surface by a load of 4.0 psi. The rotating speed of each of the polishing pad and the silicon wafer was set to 150 rpm, and the silicon dioxide layer was polished for 60 seconds. After polishing, the silicon wafer was detached from the carrier, mounted on a spin dryer, washed with distilled water, and then dried with nitrogen for 15 seconds.

15 **[00246]** (1) Average Removal Rate

[00247] For the dried silicon wafer, the layer thickness change between before and after polishing was measured using an optical interference type thickness measuring instrument (SI-F80R, Keyence). Then, the removal rate was calculated using the equation shown below. In this way, the removal rate was measured a total of 5 times, and the number
20 average value thereof was calculated as the average removal rate.

[00248] Removal rate (Å/min) = polished thickness (Å) of silicon wafer / polishing time (min)

[00249] (2) Defects

[00250] Polishing was performed in the same manner as the removal rate
25 measurement method, and the number of defects such as scratches was determined by

visually observing the polished surface of the polishing target. Specifically, after polishing, the silicon wafer was moved to a cleaner and rinsed with each of a mixture of 1% hydrogen fluoride (HF) and purified water (DIW) and a mixture of 1% nitric acid (H₂NO₃) and purified water (DIW) for 10 seconds per rinse. Then, the silicon wafer was transferred into a spin dryer, cleaned with purified water (DIW), and then dried with nitrogen for 15 seconds. For the dried silicon wafer, the change in defects between before and after polishing was visually observed using a defect measuring instrument (Tenkor, XP+).

[00251] The results of Experimental Examples 1 to 4 above are shown in Table 1 below.

10 **[00252]** [Table 1]

Item			Example 1	Example 2	Comp. Example 1	Comp. Example 2
Composition of preliminary composition	Diisocyanate	2,4-TDI	96	80	73	71
		2,6-TDI	4	5	17	16
		H ₁₂ MDI	-	15	10	13
		Total	100	100	100	100
	Polyol	PTMG (Mw 1000)	90.0	97.5	90.8	89.9
		DEG (Mw 106)	10.0	2.5	9.2	10.1
		Total	100	100	100	100
	NCO group content (wt%) of preliminary composition		6	8.0	9	9.2
Amine curing agent	Molar ratio of NH ₂ of curing agent to NCO of preliminary composition	0.75	0.70	0.96	0.94	
Process conditions	Reaction temperature (°C) for prepolymer production	80	80	80	80	

	Preheating temperature (°C) of curing mold		90	100	90	95
	Post-curing temperature (°C)		110	110	110	110
¹³ C NMR of preliminary composition	Peak position (ppm)	Fourth peak (17.5 to 20)	17.627	17.713	17.694	17.682
		Fifth peak (16 to 17.5)	17.226	17.293	17.026	16.997
	Area ratio	Fourth peak: fifth peak	3.89 : 1	6.02 : 1	3.18 : 1	1.67 : 1
¹³ C NMR of processed composition	Peak position (ppm)	First peak (15 to 18)	16.263	17.093	16.549	16.196
		Second peak (9 to 11)	10.006	10.000	10.292	9.930
		Third peak (138 to 143)	140.824	143.104	141.082	160.853
	Area ratio	Third peak: second peak	5.31 : 1	5.25 : 1	3.15 : 1	3.34 : 1
		First peak: second peak	10 : 1.08	10 : 1.60	10 : 1.72	10 : 1.66
		First peak: third peak	10 : 5.74	10 : 8.40	10 : 5.40	10 : 5.52
Physical properties of polishing layer or polishing pad	Hardness (Shore D)		43	45	58.4	56.2
	Tensile strength (N/mm ²)		14.5	18.5	21.4	22.2
	Elongation (%)		230.8	240.2	94.4	107.5
	Polishing pad cutting rate (μm/hr)		84.5	90.2	51.2	51.3

Polishing	Average removal rate (Å/min)	2357	2345	3724	3324
performance	Number of defects (ea)	4	5	0.5	1

[00253] Referring to Table 1 above, it can be confirmed that the polishing layer of each of Examples 1 and 2 was a polishing layer wherein the nuclear magnetic resonance (NMR) ¹³C spectrum of a processed composition prepared by treatment under predetermined conditions included a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and the area ratio of the third peak to the second peak was about 5:1 to about 10:1. Based on the properties corresponding thereto, such as hardness, tensile strength, elongation and cutting rate, it can be confirmed that results of polishing the semiconductor substrate using the polishing layer were very excellent.

[00254] In contrast, it can be confirmed that the polishing layers of Comparative Examples 1 and 2 showed physical properties, including high hardness and tensile strength and low elongation and cutting rate compared to the polishing layers of Examples 1 and 2, because the area ratio of the third peak to the second peak was out of the range of 5:1 to 10:1. Accordingly, it can be confirmed that the polishing pads of Comparative Examples 1 and 2 did not exhibit polishing performance on the polishing target surface at the levels shown by the polishing pads of Examples 1 and 2, and thus were inferior in terms of average polishing rate and defects.

[00255] Comparative Example 3

[00256] A diisocyanate component and a polyol component were mixed together at the ratio shown in Table 2 below. The mixture was placed in a four-neck flask and allowed to react at 80°C, thus preparing a preliminary composition containing a urethane-based prepolymer. The content of isocyanate groups (NCO groups) in the preliminary composition was adjusted to 9.2 wt%. 4,4'-methylenebis(2-chloroaniline) (MOCA) as a

curing agent was added to the preliminary composition so that the molar ratio of the NH₂ groups of the MOCA to the NCO groups in the preliminary composition was 0.94. In addition, 1.0 part by weight of a solid foaming agent (Akzonobel Corp.) as expandable particles was added to the preliminary composition. The preliminary composition was injected into a mold, having a width of 1,000 mm, a length of 1,000 mm and a height of 3 mm and preheated to 95°C, at a discharge rate of 10 kg/min. Then, a polishing layer was produced by subjecting the preliminary composition to a post-curing reaction at a temperature of 110°C.

[00257] Comparative Example 4

[00258] A diisocyanate component and a polyol component were mixed together at the ratio shown in Table 2 below. The mixture was placed in a four-neck flask and allowed to react at 80°C, thus preparing a preliminary composition containing a urethane-based prepolymer. The content of isocyanate groups (NCO groups) in the preliminary composition was adjusted to 9.5 wt%. 4,4'-methylenebis(2-chloroaniline) (MOCA) as a curing agent was added to the preliminary composition so that the molar ratio of the NH₂ groups of the MOCA to the NCO groups in the preliminary composition was 0.92. In addition, 1.0 part by weight of a solid foaming agent (Akzonobel Corp.) as expandable particles was added to the preliminary composition. The preliminary composition was injected into a mold, having a width of 1,000 mm, a length of 1,000 mm and a height of 3 mm and preheated to 100°C, at a discharge rate of 10 kg/min. Then, a polishing layer was produced by subjecting the preliminary composition to a post-curing reaction at a temperature of 110°C.

[00259] [Table 2]

Item			Example 1	Example 2	Comp. Example 1	Comp. Example 3	Comp. Example 4
Composition of preliminary composition	Diisocyanate	2,4-TDI	96	80	73	72	70
		2,6-TDI	4	5	17	16	15
		H ₁₂ MDI	-	15	10	12	15
		Total	100	100	100	100	100
	Polyol	PTMG(Mw 1000)	90.0	97.5	90.8	89.9	89.9
		DEG(Mw 106)	10.0	2.5	9.2	10.1	10.1
		Total	100	100	100	100	100
	NCO group content (wt%) of preliminary composition		6	8	9	9.2	9.5
	Molar ratio of NH ₂ of curing agent to NCO in preliminary composition		0.75	0.70	0.96	0.94	0.92
Process conditions	Reaction temperature (°C) for prepolymer production		80	80	80	80	80
	Preheating temperature (°C) of curing mold		90	100	90	95	100
	Post-curing temperature (°C)		110	110	110	110	110

[00260] Experimental Example 5: GPC Measurement of Processed Composition

[00261] About 1 g of the polishing layers of each of the Examples and the

Comparative Examples was added to 15 ml of an about 0.3 M aqueous solution of KOH. Thereafter, the KOH solution containing each polishing layer was placed in a closed pressure container having a volume of about 48 ml and subjected to depolymerization at a temperature of about 150°C at a pressure of about 3 atm for about 48 hours. Then, each of the depolymerized compositions was extracted with methylene chloride.

[00262] The weight-average molecular weight (Mw), number-average molecular weight (Mn) and peak molecular weight (Mp) of each of the extracted compositions were measured by a gel permeation chromatography (GPC) system. As controls, the Mw, Mn and Mp values of the urethane-based prepolymer contained in the preliminary composition of Example 1 were measured.

[00263] The GPC system and the measurement conditions were as follows.

[00264] Measurement system: Agilent 1260 Infinity GPC

[00265] Flow rate: 1 ml/min in THF

[00266] Injection volume: 100 µl

15 [00267] Column temperature: 40°C

[00268] Detector: RI

[00269] Column: TSKgel G1000HxL Molecular Weight Size 5060

[00270] Using the GPC measurement values, the value according to the following Equation 1 was calculated:

20 [00271] [Equation 1]

[00272]
$$\frac{M_p - M_n}{M_w - M_n}$$

[00273] wherein

[00274] Mw is the weight-average molecular weight of the depolymerized composition,

25 [00275] Mn is the number-average molecular weight of the depolymerized

composition, and

[00276] Mp is the peak molecular weight of the depolymerized composition.

[00277] [Table 3]

	Mp	Mn	Mw	PDI	Value of Equation 1
Example 1	2,418	2,320	2,559	1.1	0.41
Example 2	2,359	2,163	2,560	1.18	0.49
Comparative Example 1	3,229	2,725	3,331	1.22	0.83
Comparative Example 3	3,158	2,732	3,347	1.23	0.69
Comparative Example 4	3,216	2,730	3,247	1.19	0.94
Urethane-based prepolymer	4,032	3,040	4,281	1.41	0.80

[00278] Referring to the measurement results in Table 3 above, as a result of
5 comparing the GPC measurement results of the Examples and the Comparative Examples
with the GPC measurement results of the urethane-based prepolymer, it can be confirmed
that the positions of decomposition by depolymerization in the Examples and the
Comparative Examples were different from those in the prepolymer.

[00279] Specifically, this means that the urethane-based prepolymer is produced
10 into a polishing layer by curing, and then the portions thereof decomposed by
depolymerization are different from the portions of the prepolymer, which are bonded
together upon polymerization. It was confirmed that the Mp, Mn and Mw of Examples 1
and 2 of the present disclosure were different from those of the Comparative Examples,

and the PDIs thereof were also different from those of the Comparative Examples. In addition, it was confirmed that the values of Equation 1 in the Examples were also within the range specified in the present disclosure, and the values of Equation 1 in the Comparative Example and the prepolymer were out of the specified range.

5 **[00280]** Experimental Example 6: Evaluation of Physical Properties and Polishing Performance of Polishing Layer or Polishing Pad

[00281] (1) Average Pore Size

[00282] The diameter size of the pores of each polishing layer was measured using a particle size analyzer, and the average pore size refers to D50.

10 **[00283]** (2) Specific Gravity

[00284] The specific gravity of the window prepared according to each of the Examples and Comparative Examples was measured. Each polishing pad was cut to a size of 2 cm x 2 cm (thickness: 2 mm) and then allowed to stand in an environment with a temperature of 25°C and a humidity of $50 \pm 5\%$ for 16 hours. Next, the initial weight and
15 the weight when immersed in water were measured using an electronic densimeter, and then the density was calculated.

[00285] (3) Chatter Mark Inspection

[00286] The polishing process was performed using each of the polishing pads described in the Examples and the Comparative Examples, and then residues, scratches
20 and chatter marks appearing on each wafer (monitoring wafer) after polishing were measured using a defect inspection system (AIT XP+, KLA Tencor) under conditions of threshold 150 and die filter threshold 280.

[00287] The results of evaluating the Examples and the Comparative Examples by Experimental Examples 3, 4 and 6 are shown in Table 3 below.

25 **[00288]** [Table 4]

	Example 1	Example 2	Comp. Example 1	Comp. Example 3	Comp. Example 4
Hardness (Shore D)	43.5	53.2	56.2	57.7	58
Average pore size (μm)	21	11.2	24.1	20.7	21.5
Specific gravity (g/cc)	0.8	0.8	0.8	0.8	0.8
Tensile strength (N/mm^2)	19.5	19.82	23.2	22.3	22.3
Elongation (%)	240.5	81.3	98.2	107.5	109.1
Average removal rate ($\text{\AA}/\text{min}$)	1,825	3,458	3,724	3,357	3,650
Pits/residue	2	2.5	3	4	3.5
Chatter marks	0	0.5	1	0	0.5

[00289] Referring to the experimental results in Table 4 above, it was confirmed that the polishing pad of Example 1 showed a lower average removal rate than other polishing pads, but exhibited a very good effect in terms of defects on the silicon wafer.

[00290] In addition, it was confirmed that Example 2 maintained the average removal rate at the same level as those of the Comparative Examples, and exhibited an excellent effect in terms of defects on the wafer. This is because the average pore size of the polishing layer of Example 2 was small and the tensile strength and elongation

properties thereof were excellent.

5 **[00291]** As described above, the polishing pad according to the present disclosure includes the polishing layer having a chemical bond structure and a crosslinked structure, which correspond to the peak characteristics shown by a processed composition prepared by treating the polishing pad under predetermined conditions. Accordingly, the polishing surface of the polishing layer may exhibit appropriate hardness, and thus exhibit a polishing rate and polishing flatness within desired ranges in polishing of a polishing target. In addition, the polishing layer has an advantage in that the polishing surface thereof maintains a surface state equivalent to the initial state even with the passage of time during the polishing process, and thus the long-term polishing performance thereof does not deteriorate.

10 **[00292]** The method of fabricating a semiconductor device using the polishing pad exhibits high process efficiency in polishing of a semiconductor substrate as a polishing target, and may be effective in that the polished surface of the semiconductor substrate shows a high polishing flatness and the lowest level of defects in the final polishing results.

WHAT IS CLAIMED IS:

1. A polishing pad comprising a polishing layer,
wherein a nuclear magnetic resonance (NMR) ^{13}C spectrum of a processed
5 composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of
potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a
temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a
second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143
ppm, and
10 an area ratio of the third peak to the second peak is 5:1 to 10:1.
2. The polishing pad of claim 1, wherein
an area ratio of the first peak to the second peak is 10:1 to 10:5, and
an area ratio of the first peak to the third peak is 10:5 to 10:10.
15
3. The polishing pad of claim 1, wherein
the polishing layer comprises a cured product of a preliminary composition
containing a urethane-based prepolymer,
a nuclear magnetic resonance (NMR) ^{13}C spectrum of the preliminary composition
20 shows a fourth peak and a fifth peak in descending order of peak position (ppm) at 16 ppm
to 20 ppm,
an area ratio of the fourth peak to the fifth peak is 1:1 to 10:1.
the preliminary composition contains a reaction product of an isocyanate
compound and a polyol compound,
25 the isocyanate compound comprises an aromatic diisocyanate compound,

the polyol compound comprises a low-molecular-weight polyol having a weight-average molecular weight (Mw) of about 100 g/mol to less than about 300 g/mol and a high-molecular-weight polyol having a weight-average molecular weight (Mw) of about 300 g/mol to about 1,800 g/mol,

5 the aromatic isocyanate compound comprises 2,4-toluene diisocyanate (2,4-TDI),
the preliminary composition contains a urethane-based prepolymer comprising at least one of a first unit structure derived from 2,4-TDI subjected to urethane reaction at one end, and a second unit structure derived from 2,4-TDI subjected to urethane reaction at both ends, and

10 the preliminary composition has an isocyanate group content of 5 wt% to 11 wt%.

4. The polishing pad of claim 1, wherein the polishing layer has a value of 0.1 to 0.6 as calculated according to Equation 1 below:

[Equation 1]

15
$$\frac{M_p - M_n}{M_w - M_n}$$

wherein Mw, Mn and Mp are the molecular weights of the processed composition, measured by gel permeation chromatography (GPC),

Mw is the weight-average molecular weight of the depolymerized composition,

Mn is the number-average molecular weight of the depolymerized composition,

20 and

Mp is the peak molecular weight of the depolymerized composition.

5. The polishing pad of claim 1, wherein the processed composition has a number-average molecular weight (Mn) of 1,800 g/mol to 2,800 g/mol, a weight-average

molecular weight (Mw) of 2,000 g/mol to 3,000 g/mol, a peak molecular weight(Mp) of 2,000 g/mol to 3,000 g/mol, and a polydispersity index (PDI, Mw/Mn) of 1 to 1.2.

6. A method for producing a polishing pad, the method comprising steps of:

5 i) preparing a preliminary composition containing a reaction product of an isocyanate compound and a polyol compound;

ii) preparing a composition for producing a polishing layer containing the preliminary composition, a foaming agent and a curing agent; and

10 iii) producing a polishing layer by curing the composition for producing a polishing layer,

wherein a nuclear magnetic resonance (NMR) ^{13}C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a
15 second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and

an area ratio of the third peak to the second peak is 5:1 to 10:1.

7. The method of claim 6, wherein

20 an area ratio of the first peak to the second peak is 10:1 to 10:5,

an area ratio of the first peak to the third peak is 10:5 to 10:10,

a nuclear magnetic resonance (NMR) ^{13}C spectrum of the preliminary composition shows a fourth peak and a fifth peak in descending order of peak position (ppm) at 16 ppm to 20 ppm, and

25 an area ratio of the fourth peak to the fifth peak is 1:1 to 10:1.

8. The method of claim 6, wherein the polishing layer has a value of 0.1 to 0.6 as calculated according to Equation 1 below:

[Equation 1]

5
$$\frac{M_p - M_n}{M_w - M_n}$$

wherein Mw, Mn and Mp are the molecular weights of the processed composition, measured by gel permeation chromatography (GPC)

Mw is the weight-average molecular weight of the depolymerized composition,

Mn is the number-average molecular weight of the depolymerized composition,

10 and

Mp is the peak molecular weight of the depolymerized composition.

9. A method for fabricating a semiconductor device, the method comprising steps of:

15 providing a polishing pad comprising a polishing layer; and

placing a polishing target surface of a polishing target so as to be in contact with a polishing surface of the polishing layer and then polishing the polishing target while rotating relative to each other,

wherein the polishing target comprises a semiconductor substrate,

20 a nuclear magnetic resonance (NMR) ¹³C spectrum of a processed composition prepared by adding 1 g of the polishing layer to a 0.3 M aqueous solution of potassium hydroxide (KOH) and allowing the mixture to react in a closed container at a temperature of 150°C for 48 hours includes a first peak appearing at 15 ppm to 18 ppm, a second peak appearing at 9 ppm to 11 ppm, and a third peak appearing at 138 ppm to 143 ppm, and

an area ratio of the third peak to the second peak is 5:1 to 10:1.

10. The method of claim 9, wherein the polishing layer has a value of 0.1 to 0.6 as calculated according to Equation 1 below:

5 [Equation 1]

$$\frac{M_p - M_n}{M_w - M_n}$$

wherein M_w , M_n and M_p are the molecular weights of the processed composition, measured by gel permeation chromatography (GPC),

M_w is a weight-average molecular weight of the depolymerized composition,

10 M_n is a number-average molecular weight of the depolymerized composition,

and

M_p is a peak molecular weight of the depolymerized composition.